



PK752 (v1.0) July 10, 2015

# 100% Material Declaration Data Sheet

## Spartan®-6 Cu Wire FG484 Package

**Average Weight: 2.3564 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.038245</b>	<b>1.623%</b>
	Silicon	7440-21-3	100.00	Main material	0.038245	
<b>Die Attach Material</b>					<b>0.007051</b>	<b>0.299%</b>
	Silver	7440-22-4	77.50	Main material	0.005465	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.001058	
	Acrylate monomer	Trade Secret	7.50	Main material	0.000529	
<b>Copper Wire</b>					<b>0.007385</b>	<b>0.313%</b>
	Cu	7440-50-8	98.25	Main material	0.007256	
	Pd	7440-05-3	1.75	Dopant	0.000129	
<b>Mold Compound</b>					<b>0.851079</b>	<b>36.118%</b>
	Epoxy Resin	Trade secret	3.00	Main material	0.025532	
	Phenol Resin A	9003-35-4	3.00	Main material	0.025532	
	Phenol Resin B	Trade secret	3.00	Main material	0.025532	
	Silica(Amorphous) A	60676-86-0	72.45	Filler	0.616607	
	Silica(Amorphous) B	7631-86-9	15.00	Filler	0.127662	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.025532	
	Carbon black	1333-86-4	0.55	Color agent	0.004681	
<b>Solder Balls</b>					<b>0.460670</b>	<b>19.550%</b>
	Tin (Sn)	7440-31-5	63.00	Main material	0.290222	
	Lead (Pb)	7439-92-1	37.00	Main material	0.170448	

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Substrate					<b>0.991923</b>	<b>42.096%</b>
	Au	7440-57-5	0.867	Main material	0.008601	
	Ni	7440-02-0	8.418	Main material	0.083503	
	Cu foil	7440-50-8	2.577	Main material	0.025566	
	Cu plating	7440-50-8	16.109	Plating	0.159788	
	Continuous Filament Fiber Glass	65997-17-3	20.029	Glass Fiber	0.198668	
	BT Core	7440-50-8 N/A	35.003	Core	0.347208	
	Solder Mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 91-20-3 85954-11-6 N/A	12.541	Solder mask	0.124399	
	Prepregs	NA	4.455	Prepregs	0.044191	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
7/10/15	1.0	Initial Xilinx release

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